

REMARKS/ARGUMENTS

Reexamination of the captioned application is respectfully requested.

A. SUMMARY OF THIS AMENDMENT

By the current amendment, Applicants basically:

1. Amend independent claims 1 and 2 by including therein limitations from dependent claims 10 and 13.
2. Amend independent claim 3 by including therein limitations from dependent claim 13.
3. Cancel claims 10 and 13 without prejudice or disclaimer.
4. Respectfully traverse all prior art rejections.
5. Apprise the Examiner of the filing of a Petition to Extend.

B. PATENTABILITY OF THE CLAIMS

Claims 1, 4, 5, 7, 8, 9, 14, 15, 16, 17, 18, 19 and 20 stand rejected under 35 USC 103(a) as being unpatentable over U.S. Publication 2003/0059991 to Teramoto et al in combination with U.S. Publication 2007/0020826 to Yamazaki, applicant's admitted prior art, U.S. Publication 2004/0201874 to Yamazaki, U.S. Patent 4,584,025 to Takaoka et al and U.S. Publication 2003/0148565 to Yamanaka. Claim 2 stands rejected under 35 USC 103(a) as being unpatentable over U.S. Publication 2003/0059991 to Teramoto et al in combination with U.S. Publication 2007/0020826 to Yamazaki. Claims 3, 10, 11, 12 and 13 stand rejected under 35 USC 103(a) as being unpatentable over U.S. Publication 2003/0059991 to Teramoto et al in combination with U.S. Publication 2007/0020826 to Yamazaki and U.S. Publication 2005/014119 to Fujimura. All prior art rejections are respectfully traversed for at least the following reasons.

As amended, all non-withdrawn independent claims include a feature of high thermal conductivity material and expressly require that the high thermal conductivity

material have a thermal conductivity of at least 10 W/mK. The amendatory limitations are neither new matter nor new issues.

The office action incorrectly alleges that paragraph [0033] of the description of Teramoto teaches provision of a high thermal conductivity material. Applicants disagree: Paragraph [0033] of Teramoto does not describe high thermal conductivity material, but rather merely states that “an insulating film such as a silicon oxide film or silicon nitride film is formed...”. Silicon oxide and silicon nitride do *not* have thermal conductivity of more than 10 W/mk. Silicon oxide is recited as a low thermal conductivity material (on page 5, last line to page 6, first line of the present specification).

Moreover, paragraph [0171], Example 5 of Teramoto describes that “...there is no place to which heat escapes...”. Thus, it is represented that Teramoto does not describe nor suggest the high thermal conductivity material of Applicants’ independent claims 1 – 3.

Nor do any of Yamazaki, Takaoka, or Yamanaka describe or suggest, e.g., the high thermal conductivity material as now claimed in independent claims 1 -3.

In view of the foregoing and other considerations, all claims are deemed in condition for allowance. Accordingly, Applicant respectfully requests that all prior art rejections be withdrawn. A formal indication of allowability is earnestly solicited.

C. MISCELLANEOUS

The Commissioner is authorized to charge the undersigned's deposit account #14-1140 in whatever amount is necessary for entry of these papers and the continued pendency of the captioned application.

NAKAYAMA
Serial No. 10/687,620

Atty Dkt: 914-170
Art Unit: 2814

Should the Examiner feel that an interview with the undersigned would facilitate allowance of this application, the Examiner is encouraged to contact the undersigned.

Respectfully submitted,

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